















TXS0104E

SCES651H - JUNE 2006-REVISED MAY 2018

TXS0104E 4-Bit Bidirectional Voltage-Level Translator for Open-Drain and Push-Pull **Applications**

Features

- No Direction-Control Signal Needed
- Max Data Rates
 - 24 Mbps (Push Pull)
 - 2 Mbps (Open Drain)
- Available in the Texas Instruments NanoFree™ Package
- 1.65 V to 3.6 V on A port and 2.3 V to 5.5 V on B port $(V_{CCA} \leq V_{CCB})$
- No Power-Supply Sequencing Required V_{CCA} or V_{CCB} Can Be Ramped First
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - A Port
 - 2000-V Human-Body Model (A114-B)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
 - B Port
 - 15-kV Human-Body Model (A114-B)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- IEC 61000-4-2 ESD (B Port)
 - ±8-kV Contact Discharge
 - ±10-kV Air-Gap Discharge

2 Applications

- Handset
- Smartphone
- Tablet
- Desktop PC

3 Description

This 4-bit non-inverting translator uses two separate configurable power-supply rails. The A port is designed to track V_{CCA}. V_{CCA} accepts any supply voltage from 1.65 V to 3.6 V. V_{CCA} must be less than or equal to V_{CCB} . The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 2.3 V to 5.5 V. This allows for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.

The TXS0104E is designed so that the OE input circuit is supplied by V_{CCA}.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TXS0104ED	SOIC (14)	8.65 mm × 3.91 mm
TXS0104EPW	TSSOP (14)	5.00 mm × 4.40 mm
TXS0104EZXU	BGA (12)	2.00 mm × 2.50 mm
TXS0104ERGY	VQFN (14)	3.50 mm × 3.50 mm
TXS0104EYZT	DSBGA (12)	1.87 mm × 1.37 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Transfer Characteristics of an N-Channel **Transistor**

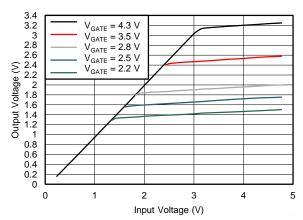




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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<u>•</u>	Changed maximum values for maximum data rate within Switching Characteristics: $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ ta	ble 15
CI	hanges from Revision F (December 2014) to Revision G	Page
•	Changed Device Information table	1
•	Deleted GXU references throughout	4
•	Added Junction temperature in the Absolute Maximum Ratings	7
•	Reformatted Electrical Characteristics	
•	Added Basics of Voltage Translation to Related Documentation	24
•	Added Receiving Notification of Documentation Updates and Community Resources	24

Changes from Revision E (August 2013) to Revision F

Changes from Revision G (September 2017) to Revision H

Page

Page

- Added Pin Configuration and Functions section, Handling Rating table, Feature Description section, Device
 Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout
 section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information
 section
- Deleted the Package thermal impedance information from the Absolute max ratings table into the Thermal Information table. Moved the T_{stg} row into the new Handling Ratings table.



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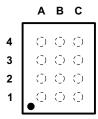
1/3	TEXAS	•
•	INSTRUMENTS	ì

Ch	nanges from Revision D (May 2008) to Revision E	Page
•	Deleted the ordering table	



5 Pin Configuration and Functions

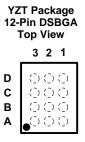
ZXU Package 12-Pin MICROSTAR JUNIOR Top View



Pin Functions: BGA

Р	IN				
NAME NO.		TYPE	DESCRIPTION		
A1	A1	I/O	Input/output A1. Referenced to V _{CCA} .		
A2	A2	I/O	Input/output A2. Referenced to V _{CCA} .		
A3	А3	I/O	Input/output A3. Referenced to V _{CCA} .		
A4	A4	I/O	Input/output A4. Referenced to V _{CCA} .		
B1 C1 I/O Input/output B1. Referenced to V _{CCB} .		Input/output B1. Referenced to V _{CCB} .			
B2	C2	I/O	Input/output B2. Referenced to V _{CCB} .		
В3	C3	I/O	Input/output B3. Referenced to V _{CCB} .		
B4	C4	I/O	Input/output B4. Referenced to V _{CCB} .		
GND	B4	_	Ground		
OE	В3	I	3-state output-mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to V_{CCA} .		
V _{CCA}	B2	_	A-port supply voltage. 1.65 V \leq V _{CCA} \leq 3.6 V and V _{CCA} \leq V _{CCB} .		
V _{CCB} B1 —		_	B-port supply voltage. 2.3 V ≤ V _{CCB} ≤ 5.5 V.		

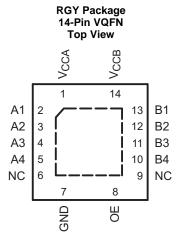




Pin Functions: DSBGA

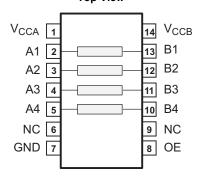
PIN TYPE		TVDE	DECODIDEION
		TYPE	DESCRIPTION
A1	A3	I/O	Input/output A1. Referenced to V _{CCA} .
A2	В3	I/O	Input/output A2. Referenced to V _{CCA} .
А3	C3	I/O	Input/output A3. Referenced to V _{CCA} .
A4	D3	I/O	Input/output A4. Referenced to V _{CCA} .
B1	A1	I/O	Input/output B1. Referenced to V _{CCB} .
B2	B1	I/O	Input/output B2. Referenced to V _{CCB} .
В3	C1	I/O	Input/output B3. Referenced to V _{CCB} .
B4	D1	I/O	Input/output B4. Referenced to V _{CCB} .
GND	D2	_	Ground
OE	C2	1	3-state output-mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to V_{CCA} .
V _{CCA}	B2	_	A-port supply voltage. 1.65 V \leq V _{CCA} \leq 3.6 V and V _{CCA} \leq V _{CCB} .
V _{CCB}	A2	_	B-port supply voltage. 2.3 V \leq V _{CCB} \leq 5.5 V.





NC - No internal connection

D and PW Package 14-Pin SOIC and TSSOP Top View



NC - No internal connection

Pin Functions: D, PW, or RGY

PIN TYPE NAME NO.		TVDE	DECORPTION	
		ITPE	DESCRIPTION	
A1	2	I/O	Input/output A1. Referenced to V _{CCA} .	
A2	3	I/O	Input/output A2. Referenced to V _{CCA} .	
А3	4	I/O	Input/output A3. Referenced to V _{CCA} .	
A4	5	I/O	Input/output A4. Referenced to V _{CCA} .	
B1	13	I/O	I/O Input/output B1. Referenced to V _{CCB} .	
B2	12	I/O	Input/output B2. Referenced to V _{CCB} .	
В3	11	I/O	Input/output B3. Referenced to V _{CCB} .	
B4	10	I/O	Input/output B4. Referenced to V _{CCB} .	
GND	7	_	Ground	
OE	8	1	3-state output-mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to V_{CCA} .	
V_{CCA}	1	_	A-port supply voltage. 1.65 V \leq V _{CCA} \leq 3.6 V and V _{CCA} \leq V _{CCB} .	
V _{CCB}	14	_	B-port supply voltage. 2.3 V ≤ V _{CCB} ≤ 5.5 V.	
Thermal Pad	_	_	For the RGY package, the exposed center thermal pad must be connected to ground	



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage, V _{CCA}		-0.5	4.6	V
Supply voltage, V _{CCB}		-0.5	6.5	V
Input voltage V (2)	A port	-0.5	4.6	V
Input voltage, V _I ⁽²⁾	B port	-0.5	6.5	
Valtage response and indicate any extent in the binb improduce an extent (2)	A port	-0.5	4.6	V
Voltage range applied to any output in the high-impedance or power-off state, $V_0^{(2)}$	B port	-0.5	6.5	
Voltage range applied to any output in the high or low state, $V_{O}^{(2)\ (3)}$	A port	-0.5	V _{CCA} + 0.5	V
	B port	-0.5	V _{CCB} + 0.5	
Input clamp current, I _{IK}	V _I < 0		-50	mA
Output clamp current, I _{OK}	V _O < 0		-50	mA
Continuous output current, I _O	·	-50	50	mA
Continuous current through each V _{CCA} , V _{CCB} , or GND		-100	100	mA
Operating junction temperature, T _J			150	°C
Storage temperature, T _{STG}		-65	150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

				VALUE	UNIT
		1 and 11 in (1)	A Port	±2000	V
	Flectrostatic Charged device model (CDM) pe		B Port	±15	kV
.,		Charged device model (CDM), per JEDEC specification	A Port	±1000	V
V _(ESD)		JESD22-C101, all pins ⁽²⁾	B Port	±1000	V
		Machina madel (MM)	A Port	±200	V
		Machine model (MM)	B Port	±200	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

³⁾ The value of V_{CCA} and V_{CCB} are provided in the recommended operating conditions table.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) (1) (2)

			V _{CCA}	V _{CCB}	MIN	MAX	UNIT
V_{CCA}	Supply voltage ⁽³⁾				1.65	3.6	V
V _{CCB}	Supply voltage ⁽³⁾				2.3	5.5	V
		A = == 1/O=	1.65 V to 1.95 V	2.3 V to 5.5 V	V _{CCI} - 0.2	V _{CCI}	
\	High lavel lavet valtage	A-port I/Os	2.3 V to 3.6 V	2.3 V to 5.5 V	V _{CCI} - 0.4	V _{CCI}	\ /
V_{IH}	High-level input voltage	B-port I/Os	1.65 V to 3.6 V	2.3 V to 5.5 V	V _{CCI} - 0.4	V _{CCI}	V
		OE input	1.65 V to 3.6 V	2.3 V to 5.5 V	V _{CCA} × 0.65	5.5	
	Low-level input voltage	A-port I/Os	1.65 V to 3.6 V	2.3 V to 5.5 V	0	0.15	
V_{IL}		B-port I/Os	1.65 V to 3.6 V	2.3 V to 5.5 V	0	0.15	V
		OE input	1.65 V to 3.6 V	2.3 V to 5.5 V	0	V _{CCA} × 0.35	
	Input transition rise or fall rate	A-port I/Os push-pull driving	1.65 V to 3.6 V	2.3 V to 5.5 V		10	
Δt/Δν		B-port I/Os push-pull driving	1.65 V to 3.6 V	2.3 V to 5.5 V		10	ns/V
		Control input	1.65 V to 3.6 V	2.3 V to 5.5 V		10	
T _A	Operating free-air temperature				-40	85	°C

6.4 Thermal Information: ZXU and YZT

		TXS0104		
	THERMAL METRIC ⁽¹⁾	ZXU (BGA MICROSTAR JUNIOR) ⁽²⁾	YZT (DSBGA)	UNIT
		12 PINS	12 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	132.0	89.2	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	98.4	0.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	68.7	14.4	°C/W
ΨЈТ	Junction-to-top characterization parameter	3.1	3.0	°C/W
ΨЈВ	Junction-to-board characterization parameter	68.2	14.4	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Thermal Information: D, PW, and RGY

		TXS0104E				
	THERMAL METRIC ⁽¹⁾	D (SOIC) ⁽¹⁾	PW (TSSOP) ⁽²⁾	RGY (VQFN) ⁽³⁾	UNIT	
		14 PINS	14 PINS	14 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	90.4	120.1	56.1	°C/W	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	50.1	49.4	68.8	°C/W	
$R_{\theta JB}$	Junction-to-board thermal resistance	45.0	61.8	32.1	°C/W	
ΨЈТ	Junction-to-top characterization parameter	14.4	6.2	3.1	°C/W	
ΨЈВ	Junction-to-board characterization parameter	44.7	61.2	32.3	°C/W	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	_	_	12.8	°C/W	

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application

 V_{CCI} is the supply voltage associated with the input port. V_{CCO} is the supply voltage associated with the output port. V_{CCA} must be less than or equal to V_{CCB} , and V_{CCA} must not exceed 3.6 V.

The package thermal impedance is calculated in accordance with JESD 51-7.

The package thermal impedance is calculated in accordance with JESD 51-7.

The package thermal impedance is calculated in accordance with JESD 51-5.



6.6 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (1) (2) (3)

F	PARAMETER	TEST CONDITIONS	V _{CCA}	V _{CCB}	MIN	TYP MA	UNIT
V_{OHA}	Port A output high voltage	$I_{OH} = -20 \mu A,$ $V_{IB} \ge V_{CCB} - 0.4 V$ $T_A = -40^{\circ}C$ to 85°C	1.65 V to 3.6 V	2.3 V to 5.5 V	V _{CCA} × 0.8		V
V _{OLA}	Port A output low voltage	$I_{OL} = 1 \text{ mA},$ $V_{IB} \le 0.15 \text{ V}$ $T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$	1.65 V to 3.6 V	2.3 V to 5.5 V		0.	4 V
V_{OHB}	Port B output high voltage	$I_{OH} = -20 \mu A,$ $V_{IA} \ge V_{CCA} - 0.2 V$ $T_A = -40^{\circ}C$ to 85°C	1.65 V to 3.6 V	2.3 V to 5.5 V	V _{CCB} × 0.8		V
V_{OLB}	Port B output low voltage	$I_{OL} = 1 \text{ mA},$ $V_{IA} \le 0.15 \text{ V}$ $T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$	1.65 V to 3.6 V	2.3 V to 5.5 V		0.	4 V
I _I	Input leakage	OE: $V_I = V_{CCI}$ or GND $T_A = 25^{\circ}$ C	1.65 V to 3.6 V	2.3 V to 5.5 V	-1		1 μΑ
'I current	$V_I = V_{CCI}$ or GND $T_A = -40$ °C to 85°C	1.65 V to 3.6 V	2.3 V to 5.5 V	-2		2	
, High-impedance state	A or B port: OE = V _{IL} T _A = 25°C	1.65 V to 3.6 V	2.3 V to 5.5 V	-1		1	
l _{OZ}	output current	A or B port: OE = V _{IL} T _A = -40°C to 85°C	1.65 V to 3.6 V	2.3 V to 5.5 V	-2		μA 2
	V _{CCA} supply current	$V_I = V_O = Open,$	1.65 V to V _{CCB}	2.3 V to 5.5 V		2.	4
I_{CCA}		$I_{O} = 0$	3.6 V	0		2.	2 μA
		$T_A = -40$ °C to 85°C	0	5.5 V		-	1
		V _I = V _O = Open,	1.65 V to V _{CCB}	2.3 V to 5.5 V		1	2
I_{CCB}	V _{CCB} supply current	$I_O = 0$	3.6 V	0		-	1 μΑ
		$T_A = -40$ °C to 85°C	0	5.5 V			1
I _{CCA} + I _{CCB}	Combined supply current	$V_I = V_O = Open,$ $I_O = 0$ $T_A = -40$ °C to 85°C	1.65 V to V _{CCB}	2.3 V to 5.5 V		14.	4 μA
0	land an alterna	OE: T _A = 25°C	3.3 V	3.3 V		2.5	
Cı	C _I Input capacitance	OE: $T_A = -40$ °C to 85°C	3.3 V	3.3 V		3.	pF 5
		A port:	3.3 V	3.3 V		5	
0	Input-to-output	T _A = 25°C	3.3 V	3.3 V		6.	5
C _{io}		B port:	3.3 V	3.3 V		12	pF
		$T_A = -40$ °C to 85°C		3.3 V		16.	5

 $[\]begin{array}{ll} \hbox{(1)} & V_{CCI} \ \hbox{is the supply voltage associated with the input port.} \\ \hbox{(2)} & V_{CCO} \ \hbox{is the supply voltage associated with the output port.} \\ \hbox{(3)} & V_{CCA} \ \hbox{must be less than or equal to V_{CCB}, and V_{CCA} must not exceed 3.6 V.} \\ \end{array}$



6.7 Timing Requirements: $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (unless otherwise noted)

					MIN	MAX	UNIT
Data sata				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		24	Mhna
	Data rate	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		2	Mbps
		Push-pull driving	Data inputs	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	41		20
t _w	Pulse duration	Open-drain driving	Data inputs	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	500		ns

6.8 Timing Requirements: $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

					MIN	MAX	UNIT
Data rata		Push-pull driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $CCB = 3.3 \text{ V} \pm 0.3 \text{ V}$ $CCB = 5 \text{ V} \pm 0.5 \text{ V}$	24		Mbps
	Data rate Open-drain driving			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		2	IVIDPS
	t Pulse duration	Push-pull driving	Data inputs	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	41		ns
t _w	ruise duration	Open-drain driving	Data inputs	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $CCB = 3.3 \text{ V} \pm 0.3 \text{ V}$ $CCB = 5 \text{ V} \pm 0.5 \text{ V}$	500		115

6.9 Timing Requirements: $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted)

					MIN	MAX	UNIT
Data rata		Push-pull driving		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		24	Mbps
	Data rate Open-drain driving			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		2	ivibps
	Dulan duration	Push-pull driving	Data inputs	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	41		20
t _w	Pulse duration	Open-drain driving	Data inputs	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	500		ns



6.10 Switching Characteristics: $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS	MIN	MAX	UNIT	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		4.6		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.7		
	Propagation			$V_{CCB} = 5 V \pm 0.5 V$		5.8		
PHL	delay time (high-to-low output)			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2.9	8.8		
			Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.9	9.6		
		A 4- D		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	3	10		
		A-to-B		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		6.8	ns	
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		6.8		
	Propagation			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		7		
PLH	delay time (low-to-high output)			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	45	260		
	(3 3 4 4 4 7		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	36	208		
				$V_{CCB} = 5 V \pm 0.5 V$	27	198		
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		4.4		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.5		
	Propagation delay time (high-to-low output)			$V_{CCB} = 5 V \pm 0.5 V$		4.7		
PHL				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.9	5.3	ns	
	(g.: to .o.: oatpat)		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.1	4.4		
		D (- A		$V_{CCB} = 5 V \pm 0.5 V$	1.2	4		
		B-to-A		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		5.3		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.5		
	Propagation			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		0.5		
PLH	delay time (low-to-high output)		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	45	175			
	()		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	36	140		
				$V_{CCB} = 5 V \pm 0.5 V$	27	102		
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		200	ns	
en	Enable time	OE-to-A o	or B	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		200		
				$V_{CCB} = 5 V \pm 0.5 V$		200	=	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		50		
dis	Disable time	OE-to-A o	or B	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		40	ns	
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		35		
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	3.2	9.5		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.3	9.3		
		A-port		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	2	7.6	_	
rA	Input rise time	rise time		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	38	165	ns	
			Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	30	132	_	
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	22	95	_	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	4	10.8		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.7	9.1	1	
		B-port		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	2.7	7.6	=	
rB	Input rise time	rise time		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	34	145	ns	
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	23	106	-		
			Open-drain driving	$V_{CCB} = 5.0 \text{ V} \pm 0.5 \text{ V}$	10	58	-	



Switching Characteristics: $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (continued)

over recommended operating free-air temperature range, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS	MIN	MAX	UNIT	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2	5.9		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.9	6		
	Input fall time	A-port		$V_{CCB} = 5 V \pm 0.5 V$	1.7	13.3	200	
t _{fA}	Input fall time	fall time		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	4.4	6.9	ns	
			Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	4.3	6.4		
				$V_{CCB} = 5 V \pm 0.5 V$	4.2	6.1		
			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2.9	7.6			
	Input fall time	t fall time B-port fall time	Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.8	7.5		
t_{fB}				$V_{CCB} = 5 V \pm 0.5 V$	2.8	8.8	ns	
			Open-drain driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	6.9	13.8		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	7.5	16.2		
				$V_{CCB} = 5 V \pm 0.5 V$	7	16.2		
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		1		
t _{SK(O)}	Skew (time), output	Channel-t	o-channel skew	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		1	ns	
				$V_{CCB} = 5 V \pm 0.5 V$		1		
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	24			
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	24			
	Maximum data rata			$V_{CCB} = 5 V \pm 0.5 V$	24		Mhno	
	waxiiiiuiii data fate	aximum data rate		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2		Mbps	
		Open-drain driving		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2			
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	2			



6.11 Switching Characteristics: $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

	PARAMETER		TEST CON	IDITIONS	MIN	MAX	UNIT
				V _{CCB} = 2.5 V ± 0.2 V		3.2	
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		3.3	
	Propagation			$V_{CCB} = 5 V \pm 0.5 V$		3.4	
t _{PHL}	delay time (high-to-low output)	A-to-B		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.7	6.3	
	(9		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2	6	
				$V_{CCB} = 5 V \pm 0.5 V$	2.1	5.8	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		3.5	ns
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.1	
	Propagation			$V_{CCB} = 5 V \pm 0.5 V$		4.4	
PLH	delay time (low-to-high output)	A-to-B		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	43	250	
	(ion to ingli output)		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	36	206	
				$V_{CCB} = 5 V \pm 0.5 V$	27	190	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		3	
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		3.6	1
	Propagation			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		4.3	1
PHL	_{IL} delay time (high-to-low output)	B-to-A		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.8	4.7	
	(ingit to lott output)		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.6	4.2	
				$V_{CCB} = 5 V \pm 0.5 V$	1.2	4	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		2.5	ns
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		1.6	
	Propagation	D		$V_{CCB} = 5 V \pm 0.5 V$		0.7	
PLH	H delay time (low-to-high output)	B-to-A		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	44	170	
	(12.11.12.1.19.1.2.14.1.17		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	37	140	
				$V_{CCB} = 5 V \pm 0.5 V$	27	103	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		200	ns
en	Enable time	OE-to-A	or B	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		200	
				$V_{CCB} = 5 V \pm 0.5 V$		200	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		50	
dis	Disable time	OE-to-A	or B	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		40	ns
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		35	1
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2.8	7.4	
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.6	6.6	1
	Inner de la constant	A-port		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	1.8	5.6	1
rA	Input rise time	rise time		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	34	149	ns
			Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	28	121	1
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	24	89	1
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	3.2	8.3	
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.9	7.2	1
		B-port		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	2.4	6.1	1
rB	Input rise time		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	35	151	ns	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	24	112	
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	12	64	



Switching Characteristics: $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (continued)

over recommended operating free-air temperature range, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

	PARAMETER		TEST CON	IDITIONS	MIN	MAX	UNIT
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	1.9	5.7	
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.9	5.5	
	Input fall time	A-port		$V_{CCB} = 5 V \pm 0.5 V$	1.8	5.3	ns
t _{fA}	input fail time	fall time $V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$ 4.4	fall time	6.9	IIS		
			Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	4.3	6.2	
				$V_{CCB} = 5 V \pm 0.5 V$	4.2	5.8	
			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2.2	7.8		
		Push-pull driving $V_{CCB} = 3.3 \text{ V} \pm 0.3$		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.4	6.7	
	Innut fall time	B-port		$V_{CCB} = 5 V \pm 0.5 V$	2.6	6.6	ns
t _{fB}	Input fall time	fall time	Me Open-drain driving	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	5.1	8.8	
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	5.4	9.4	
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	5.4	10.4	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		1	
t _{SK(O)}	Skew (time), output	Channel-	to-channel skew	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		1	ns
				$V_{CCB} = 5 V \pm 0.5 V$		1	
				$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	24		
			Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	24		
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	24		Mhna
	Maximum data rate	Open-drain driving		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2		Mbps
			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2			
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	2		



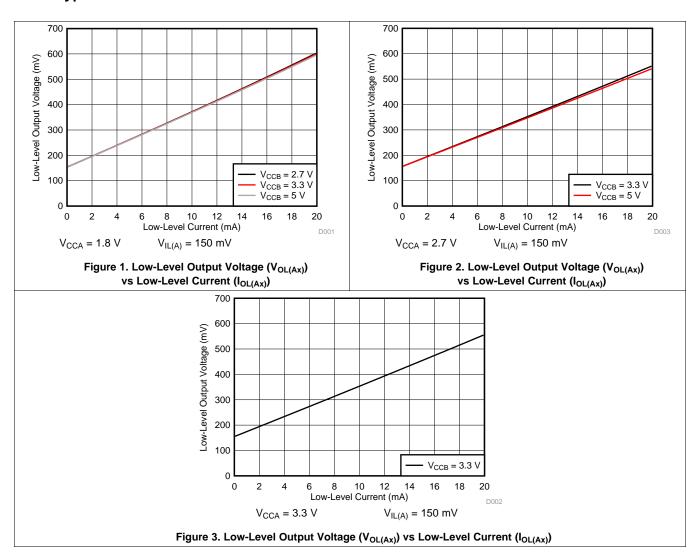
6.12 Switching Characteristics: $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$

over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS	MIN	MAX	UNIT	
			Decade weell alors do as	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		2.4		
	Propagation		Push-pull driving	V _{CCB} = 5 V ± 0.5 V		3.1		
t _{PHL}	delay time (high-to-low output)			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.3	4.2		
	() ,	A (- D	Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	1.4	4.6		
		A-to-B	December and the state of	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4.2	ns	
	Propagation		Push-pull driving	$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		4.4		
t _{PLH}	delay time (low-to-high output)			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	36	204		
	() ()		Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	28	165		
			December and definitions	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		2.5		
	Propagation		Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$		3.3		
t _{PHL}	delay time (high-to-low output)		On a substitute of the su	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1	124		
	(3,	D (- A	Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	1	97		
		B-to-A	5	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		2.5	ns	
	Propagation		Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$		2.6		
t _{PLH}	PLH delay time (low-to-high output)			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	3	139		
			Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	3	105		
		0=		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		200		
t _{en}	Enable time	OE-to-A o	rВ	$V_{CCB} = 5 V \pm 0.5 V$		200	ns	
	5	0=	_	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		40		
dis	Disable time OE-to-A o	rВ	$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		35	ns		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.3	5.6		
		A-port	Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$	1.9	4.8		
t _{rA}	Input rise time	rise time		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	25	116	ns	
			Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	19	85		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.5	6.4		
		B-port	Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$	2.1	7.4		
t _{rB}	Input rise time	rise time		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	26	116	ns	
			Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	26	116		
			5	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2	5.4		
		A-port fall	Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$	1.9	5		
t _{fA}	Input fall time	time		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	4.3	6.1	ns	
			Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	4.2	5.7		
				$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2.3	7.4		
_		B-port fall	Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$	2.4	7.6		
t _{fB}	Input fall time	time		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	5	7.6	ns	
			Open-drain driving	$V_{CCB} = 5 V \pm 0.5 V$	4.8	8.3		
1	Oleans (Care)	01		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		1		
t _{SK(O)}	Skew (time), output	Channel-to	o-channel skew	$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		1	ns	
			Push-pull driving V _{CCB} V _{CCB}	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	24			
				$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	24			
	Maximum data rate			$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2		Mbps	
			Open-drain driving	$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	2			



6.13 Typical Characteristics



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7 Parameter Measurement Information

7.1 Load Circuits

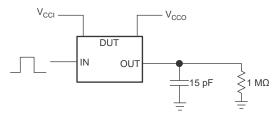


Figure 4. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using a Push-Pull Driver

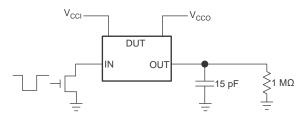
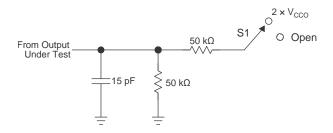


Figure 5. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using an Open-Drain Driver



TEST	S1
t _{PZL} / t _{PLZ} (t _{dis})	2 × V _{CCO}
t _{PHZ} / t _{PZH} (t _{en})	Open

Figure 6. Load Circuit for Enable-Time and Disable-Time Measurement

- 1. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- 2. t_{PZL} and t_{PZH} are the same as t_{en} .
- 3. V_{CCI} is the V_{CC} associated with the input port.
- 4. V_{CCO} is the V_{CC} associated with the output port.



7.2 Voltage Waveforms

The outputs are measured one at a time, with one transition per measurement. All input pulses are supplied by generators that have the following characteristics:

- PRR ≤ 10 MHz
- $Z_O = 50 \Omega$
- dv/dt ≥ 1 V/ns

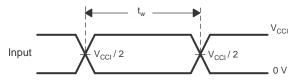


Figure 7. Pulse Duration

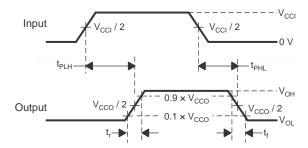
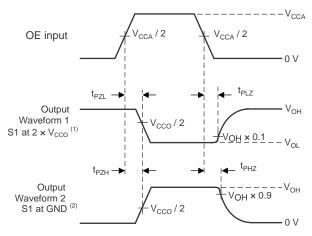


Figure 8. Propagation Delay Times



- (1) Waveform 1 is for an output with internal such that the output is high, except when OE is high (see Figure 6).
- (2) Waveform 2 is for an output with conditions such that the output is low, except when OE is high.

Figure 9. Enable and Disable Times

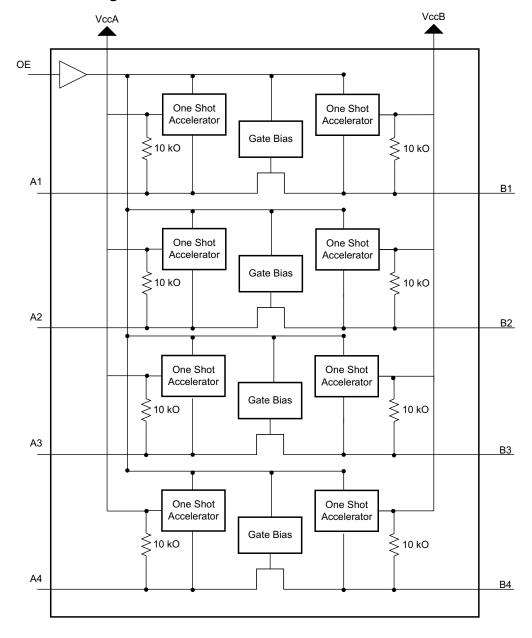


8 Detailed Description

8.1 Overview

The TXS0104E device is a directionless voltage-level translator specifically designed for translating logic voltage levels. The A port is able to accept I/O voltages ranging from 1.65 V to 3.6 V, while the B port can accept I/O voltages from 2.3 V to 5.5 V. The device is a pass gate architecture with edge rate accelerators (one shots) to improve the overall data rate. 10-k Ω pullup resistors, commonly used in open drain applications, have been conveniently integrated so that an external resistor is not needed. While this device is designed for open drain applications, the device can also translate push-pull CMOS logic outputs.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Architecture

The TXS0104E architecture (see Figure 10) does not require a direction-control signal in order to control the direction of data flow from A to B or from B to A.

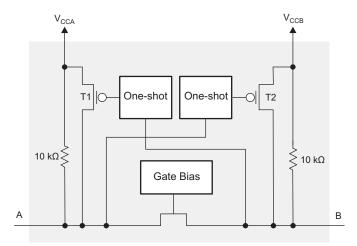


Figure 10. Architecture of a TXS01xx Cell

Each A-port I/O has an internal $10-k\Omega$ pullup resistor to V_{CCA} , and each B-port I/O has an internal $10-k\Omega$ pullup resistor to V_{CCB} . The output one-shots detect rising edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1, T2) for a short duration which speeds up the low-to-high transition.

8.3.2 Input Driver Requirements

The fall time (t_{fA} , t_{fB}) of a signal depends on the output impedance of the external device driving the data I/Os of the TXS0104E device. Similarly, the t_{PHL} and maximum data rates also depend on the output impedance of the external driver. The values for t_{fA} , t_{fB} , t_{PHL} , and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50 Ω .

8.3.3 Power Up

During operation, ensure that $V_{CCA} \le V_{CCB}$ at all times. During power-up sequencing, $V_{CCA} \ge V_{CCB}$ does not damage the device, so any power supply can be ramped up first.

8.3.4 Enable and Disable

The TXS0104E device has an OE input that disables the device by setting OE low, which places all I/Os in the high-impedance state. The disable time (t_{dis}) indicates the delay between the time when the OE pin goes low and when the outputs actually enter the high-impedance state. The enable time (t_{en}) indicates the amount of time the user must allow for the one-shot circuitry to become operational after the OE pin is taken high.

8.3.5 Pullup and Pulldown Resistors on I/O Lines

Each A-port I/O has an internal $10-k\Omega$ pullup resistor to V_{CCA} , and each B-port I/O has an internal $10-k\Omega$ pullup resistor to V_{CCB} . If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to V_{CCA} or V_{CCB} (in parallel with the internal $10-k\Omega$ resistors).

8.4 Device Functional Modes

The TXS0104E device has two functional modes, enabled and disabled. To disable the device set the OE input low, which places all I/Os in a high impedance state. Setting the OE input high will enable the device.



9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The TXS0104E device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXS0104E device is ideal for use in applications where an open-drain driver is connected to the data I/Os. The TXS0104E device can also be used in applications where a push-pull driver is connected to the data I/Os, but the TXB0104 device might be a better option for such push-pull applications.

9.2 Typical Application

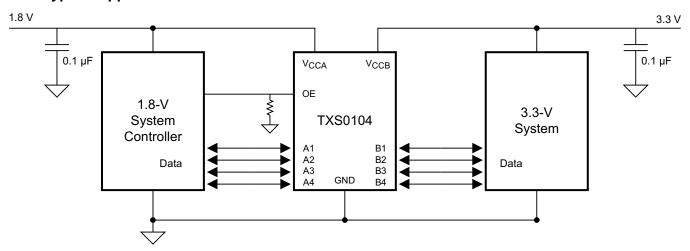


Figure 11. Application Schematic

9.2.1 Design Requirements

For this design example, use the parameters listed in Table 1.

Table 1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.65 to 3.6 V
Output voltage range	2.3 to 5.5 V



9.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- · Input voltage range
 - Use the supply voltage of the device that is driving the TXS0104E device to determine the input voltage range. For a valid logic high the value must exceed the V_{IH} of the input port. For a valid logic low the value must be less than the V_{IL} of the input port.
- Output voltage range
 - Use the supply voltage of the device that the TXS0104E device is driving to determine the output voltage range.
 - The TXS0104E device has 10-k Ω internal pullup resistors. External pullup resistors can be added to reduce the total RC of a signal trace if necessary.
 - An external pull down resistor decreases the output V_{OH} and V_{OL} . Use Equation 1 to calculate the V_{OH} as a result of an external pull down resistor.

$$V_{OH} = V_{CCx} \times R_{PD} / (R_{PD} + 10 \text{ k}\Omega) \tag{1}$$

where

 V_{CCx} is the supply voltage on either V_{CCA} or V_{CCB} R_{PD} is the value of the external pull down resistor

9.2.3 Application Curve

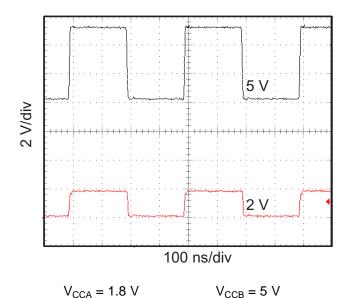


Figure 12. Level-Translation of a 2.5-MHz Signal



10 Power Supply Recommendations

The TXS0104E device uses two separate configurable power-supply rails, V_{CCA} and V_{CCB} . V_{CCB} accepts any supply voltage from 2.3 V to 5.5 V and V_{CCA} accepts any supply voltage from 1.65 V to 3.6 V as long as Vs is less than or equal to V_{CCB} . The A port and B port are designed to track V_{CCA} and V_{CCB} respectively allowing for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

The TXS0104E device does not require power sequencing between V_{CCA} and V_{CCB} during power-up so the power-supply rails can be ramped in any order. A V_{CCA} value greater than or equal to V_{CCB} ($V_{CCA} \ge V_{CCB}$) does not damage the device, but during operation, V_{CCA} must be less than or equal to V_{CCB} ($V_{CCA} \le V_{CCB}$) at all times.

The output-enable (OE) input circuit is designed so that it is supplied by V_{CCA} and when the (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pulldown resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The minimum value of the pulldown resistor to ground is determined by the current-sourcing capability of the driver.

11 Layout

11.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines is recommended.

- · Bypass capacitors should be used on power supplies.
- Short trace lengths should be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than
 the one shot duration, approximately 30 ns, ensuring that any reflection encounters low impedance at the
 source driver.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements

11.2 Layout Example

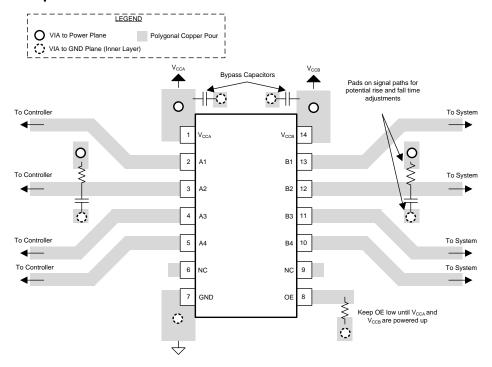


Figure 13. TXS0104E Layout Example



12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, Effects of External Pullup and Pulldown Resistors on TXS and TXB Devices application report
- Texas Instruments, Basics of Voltage Translation application report
- Texas Instruments, A Guide to Voltage Translation With TXS-Type Translators application report

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community T's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

NanoFree, E2E are trademarks of Texas Instruments. All other trademarks are the property of their respective owners.

12.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.





24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TXS0104ED	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXS0104E	Samples
TXS0104EDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXS0104E	Samples
TXS0104EDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXS0104E	Samples
TXS0104EPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YF04E	Samples
TXS0104EPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	YF04E	Samples
TXS0104ERGYR	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	YF04E	Samples
TXS0104ERGYRG4	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	YF04E	Samples
TXS0104EYZTR	ACTIVE	DSBGA	YZT	12	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(2HN, 2N, 2N7)	Samples
TXS0104EZXUR	ACTIVE	BGA MICROSTAR JUNIOR	ZXU	12	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	YF04E	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

24-Aug-2018

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TXS0104E:

Automotive: TXS0104E-Q1

NOTE: Qualified Version Definitions:

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 30-Apr-2018

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All differsions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXS0104EDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TXS0104EPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TXS0104ERGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
TXS0104EYZTR	DSBGA	YZT	12	3000	180.0	8.4	1.49	1.99	0.75	4.0	8.0	Q2
TXS0104EZXUR	BGA MI CROSTA R JUNI OR	ZXU	12	2500	330.0	8.4	2.3	2.8	1.0	4.0	8.0	Q2

www.ti.com 30-Apr-2018



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXS0104EDR	SOIC	D	14	2500	367.0	367.0	38.0
TXS0104EPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TXS0104ERGYR	VQFN	RGY	14	3000	367.0	367.0	35.0
TXS0104EYZTR	DSBGA	YZT	12	3000	182.0	182.0	20.0
TXS0104EZXUR	BGA MICROSTAR JUNIOR	ZXU	12	2500	336.6	336.6	28.6

YZT (R-XBGA-N12)

(CUSTOM) DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- G. Package complies to JEDEC MO-241 variation BA.



RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No—Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters



RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat—Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com http://www.ti.com.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



ZXU (S-PBGA-N12)

PLASTIC BALL GRID ARRAY



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. This package is a lead-free solder ball design.



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